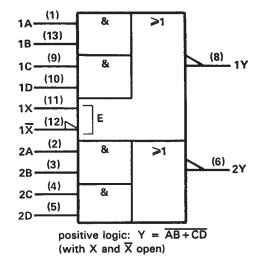
- Package Options Include Plastic and Ceramic DIPs and Ceramic Flat Packages
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent 2-wide 2-input AND-OR-INVERT gates with one gate expandable. They perform the Boolean function $Y = \overline{AB + CD}$ with X and \overline{X} left open.

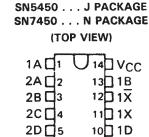
The SN5450 is characterized for operation over the full military temperature range of $-55\,^{\circ}$ C to 125 °C. The SN7450 is characterized for operation from 0 °C to 70 °C.

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for J and N packages.



2Y ☐ 6

GND 17

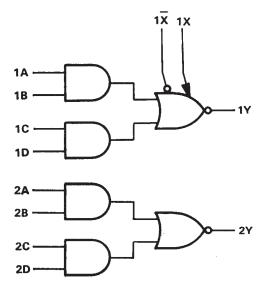
SN5450 . . . W PACKAGE (TOP VIEW)

9 1 C

8 1Y

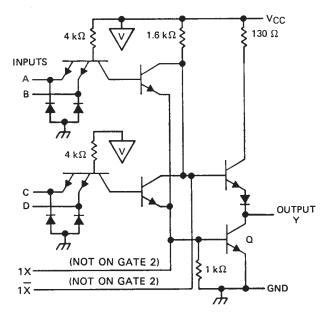
1X 🗖	1	U 14	þ	1D
1X	2	13	þ	1C
1АЦ	3	12	þ	1Y
vcc□	4	11	þ	GND
18□	5	10	þ	2Y
2A 🗆	6	9	þ	2D
2B[7	8	þ	2C

logic diagram (positive logic)





schematic (each AND-OR-INVERT gate)



Resistor values shown are nominal. If expander is not used, leave X and \overline{X} open.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage	5.5 V
Operating free-air temperature range:	SN545055°C to 125°C
Operating free an temperature range.	SN7450 0°C to 70°C
	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN5450, SN7450 **DUAL 2-WIDE 2-INPUT AND-OR-INVERT GATES (ONE GATE EXPANDABLE)**

SDLS112 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

			SN5450			SN7450			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.8			0.8	V	
ЮН	High-level output current			- 0.4			- 0.4	mA	
loL	Low-level output current			16			16	mΑ	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		- 0011DITIONO+			SN5450)		UNIT		
PARAMETER	TES	T CONDITIONS		MIN	TYP‡	MAX	MIN	TYP‡	MAX	ONT
V _{IK}	V _{CC} = MIN,	I ₁ = 12 mA				1.5			- 1.5	V
V _{OH}	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		V
Vol	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
l _l	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
t _{IH}	V _{CC} = MAX,	V _{IH} = 2.4 V				40			40	μΑ
IIL	V _{CC} = MAX,	V _{IL} = 0.4 V				- 1.6			– 1.6	mΑ
loss	V _{CC} = MAX			- 20		- 55	- 18		– 55	mA
ГССН	V _{CC} = MAX,	V ₁ = 0 V			4	8		4	8	mA
¹ CCL	V _{CC} = MAX,	See Note 2			7.4	14		7.4	14	mA
ı⊼·¶	$V\overline{\chi}\chi = 0.4 V$,	I _{OL} = 16 mA				- 2.9			- 3.1	mA
.	$I_X + I_{\overline{X}} = 0.41 \text{ mA},$	$R\overline{\chi}\chi = 0$,	I _{OL} = 16 mA			1.1				V
VBE(Q)	$1_X + 1_{\overline{X}} = 0.62 \text{ mA},$	$R\overline{\chi}\chi = 0$,	I _{OL} = 16 mA						1	
., ¶	I _X = 0.15 mA,	$I\overline{\chi} = -0.15 \mathrm{mA}$	I _{OH} = - 0.4 mA	2.4	3.4					V
VIK VOH VOL II IIH IIL IOS§ ICCH ICCL	$I_X = 0.27 \text{ mA},$	$I\overline{X} = -0.27 \text{ mA},$	I _{OH} = - 0.4 mA				2.4	3.4		<u> </u>
v •	$I_X + I_{\overline{X}} = 0.3 \text{ mA},$	$R\overline{\chi}X = 138 \Omega$,	I _{OL} = 16 mA		0.2	0.4				V
VOH VOL I; IIH IIL IOS§ ICCH ICCL IX¶ VBE(Q)¶	$I_X + I_{\overline{X}} = 0.43 \text{ mA},$					0.2	0.4	<u> L'</u>		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$ (see note 3)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
┝	tPLH			$R_L = 400 \Omega$, $C_L = 15 pF$		13	22	ns
ŀ	tPHL	Any	Y	Expander pins open		8	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time.

[¶] Using expander inputs, V_{CC} = MIN, T_A = MIN, except typical values. NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.





19-Feb-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00501BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00501BCA	Samples
M38510/00501BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00501BCA	Samples
M38510/00501BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00501BCA	Samples
SN5450J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5450J	Sample
SN5450J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5450J	Sample
SNJ5450J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5450J	Sample
SNJ5450J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5450J	Sample
SNJ5450W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5450W	Sample
SNJ5450W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5450W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

19-Feb-2021

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



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